Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP X140 40G QSFP+ LC LR4 SM 10km 1310nm Transceiver（JG661A）
HP X140 40G QSFP+ MPO MM 850nm CSR4 300m Transceiver（JG709A）
HP X140 40G QSFP+ MPO SR4 Transceiver（JG325B）

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	0（for SFP/SFP+/QSFP+/XFP） 1（for CFP）
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

(gel/paste) and toner		
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver, small flatblade, Phillips, Torx, or hex as needed	
Pliers, needle nose or similar	
Tweezers, solder iron	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

For SFP/SFP+/QSFP+/XFP:

1. If the optical transceiver has a sheet metal housing, it will be held in place with push tabs. Use a small, flatblade screwdriver to pry out the push tab.
2. With the latch bail pulled in line with the transceiver, pull the sheet metal housing from the backshell. Pliers may be useful in this step. If the housing is difficult to remove, a flatblade screwdriver can be use to pry part of it off, with pliers used to completely pull the housing off.
3. If the optical transceiver has a completely die cast shell with a separate lid, remove the screws holding it in place with the appropriate screwdriver and remove the lid.
4. If the internal PCA is not fixed to the backshell, use a flatblade screwdriver to pry it out along with other mechanical components that may be used.
5. If the PCA is fixed to the backshell with a mounting screw, use the appropriate type of screwdriver to remove the screw, then follow the instructions in Step 4.
6. The optical transceiver may have a separate, sheetmetal EMI shield close to the front. Use a small, flatblade screwdriver to pry it off.

For CFP:

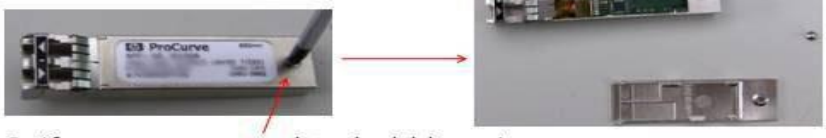
1. Loose the screw in top housing by screwdriver
2. Open the housing
3. Desoldering the OSA with solder iron
4. Split OSA and PCBA

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Note: The following flowchart is prepared for SFP as sample.

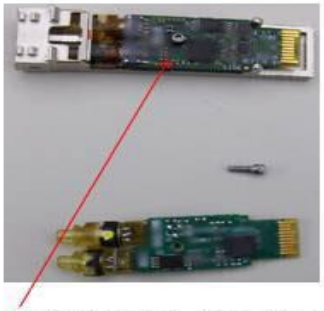
1. Pry out all retention tabs

2. Pull sheetmetal shell off



3. If screws are used to hold housing together, remove using correct screwdriver

4. Typical components



5. If present, remove screw holding PCA to housing

6. If necessary, remove EMI shield. Typical shield is shown here.

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details

4. Revised record

Date	Version	Author	Modify content
2013.08.06	V0	Pantao 06637	Initial version